LP3995 Micropower 150mA CMOS Voltage Regulator with Active Shutdown

Check for Samples: LP3995

FEATURES

- **5 pin DSBGA Package**
- **6 pin WSON Package**
- **Stable With Ceramic Capacitor**
- **Logic Controlled Enable**
- **Fast Turn-On**
- **Active Disable for Fast Turn-Off**
- **Thermal-overload and Short-Circuit Protection**
- **−40 to +125°C Junction Temperature Range for Operation**

APPLICATIONS

- **GSM Portable Phones**
- **CDMA Cellular Handsets**
- **Wideband CDMA Cellular Handsets**
- **Bluetooth Devices**
- **Portable Information Appliances**

KEY SPECIFICATIONS

- **Input Range: 2.5V to 6.0V**
- **Accurate Output Voltage: ±75mV / 2%**
- **Typical Dropout with 150 mA Load: 60mV**
- **Virtually Zero Quiescent Current when Disabled**
- **Low Output Voltage Noise**
- **Stable with an Output Capacitor of 1µF**
- **Output Current: 150mA**
- **Fast Turn-on: 30µs (Typ.)**
- **Fast Turn-off: 175µs (Typ.)**

DESCRIPTION

The LP3995 linear regulator is designed to meet the requirements of portable battery-powered applications and will provide an accurate output voltage with low noise and low quiescent current. Ideally suited for powering RF/Analog devices, this device will also be used to meet more general circuit needs in which a fast turn-off is essential.

For battery powered applications the low dropout and low ground current provided by the device allows the lifetime of the battery to be maximized. The Enable(/Disable) control allows the system to further extend the battery lifetime by reducing the power consumption to virtually zero.

The Enable(/Disable) function on the device incorporates an active discharge circuit on the output for faster device shutdown. Where the fast turn-off is not required the LP3999 linear regulator is recommended.

The LP3995 also features internal protection against short-circuit currents and over-temperature conditions.

The LP3995 is designed to be stable with small 1.0 µF ceramic capacitors. The small outline of the LP3995 DSBGA package with the required ceramic capacitors can realize a system application within minimal board area.

Performance is specified for a −40°C to +125°C temperature range.

The device is available in DSBGA package and WSON package. For other package options contact your local TI sales office.

The device is available in fixed output voltages in the ranges 1.5V to 3.3V. For availability, please contact your local TI sales office.

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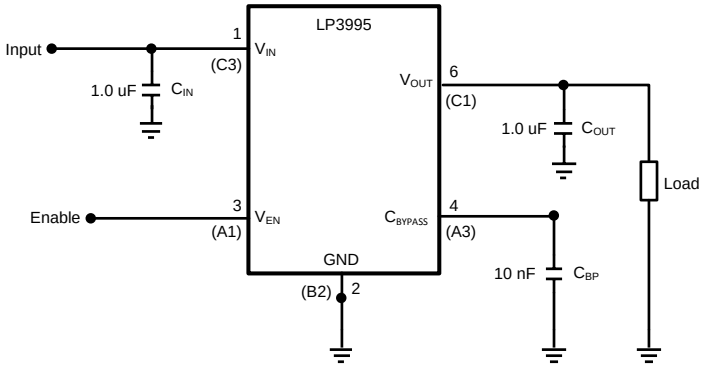
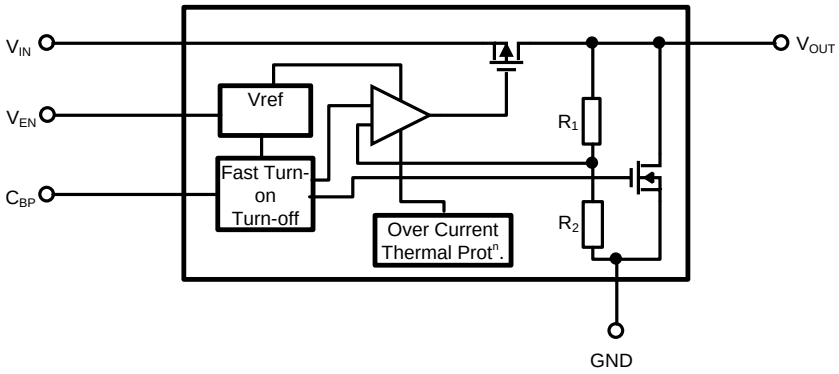
Typical Application Circuit



Block Diagram



PIN DESCRIPTION (5 PIN DSBGA and 6 PIN WSON)

Pin No.		Symbol	Name and Function
DSBGA	WSON		
A1	3	V_{EN}	Enable Input; Disables the Regulator when ≤ 0.4V. Enables the regulator when ≥ 0.9V
B2	2	GND	Common Ground
C1	6	V_{OUT}	Voltage output. Connect this output to the load circuit.
C3	1	V_{IN}	Voltage Supply Input
A3	4	C_{BYPASS}	Bypass Capacitor connection. Connect a 0.01 µF capacitor for noise reduction.
	5	N/C	No internal connection. There should not be any board connection to this pin.
	Pad	GND	Ground connection. Connect to ground plane for best thermal conduction.

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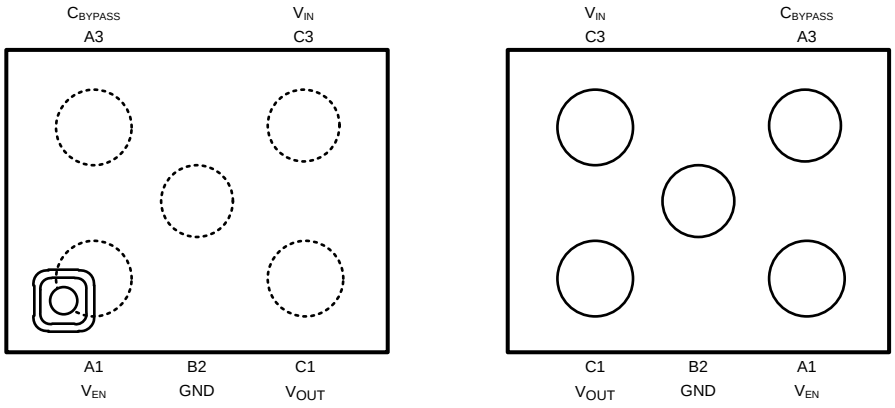
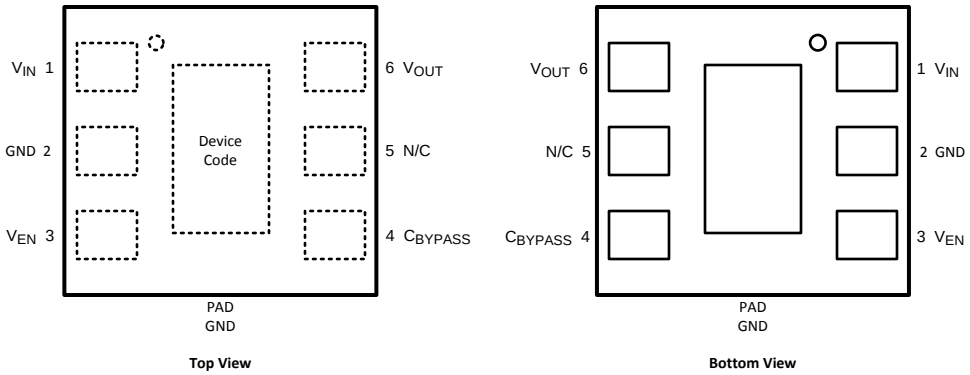
CONNECTION DIAGRAMS



5 Bump DSBGA Package
See Package Number YZR0005



6 Pin WSON Package (SOT-23 Footprint)
See Package Number NGD0006A

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

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Absolute Maximum Ratings (1) (2) (3)

Input Voltage (V_{IN})	−0.3 to 6.5V
Output Voltage	−0.3 to (V_{IN} + 0.3V) to 6.5V (max)
Enable Input Voltage	−0.3 to 6.5V
Junction Temperature	150°C
Lead/Pad Temperature (4)	
DSBGA	260°C
WSON	235°C
Storage Temperature	−65 to +150°C
Continuous Power Dissipation (5)	Internally Limited
ESD (6)	
Human Body Model	2 kV
Machine Model	200V

(1) Absolute Maximum Ratings are limits beyond which damage to the device may occur. Operating Ratings are conditions under which operation of the device is guaranteed. Operating Ratings do not imply guaranteed performance limits. For guaranteed performance limits and associated test conditions, see the Electrical Characteristics tables.
(2) All voltages are with respect to the potential at the GND pin.
(3) **If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office / Distributors for availability and specifications.**
(4) For information regarding the DSBGA package, see the TI AN-1112 Application Report (SNVA009). For information regarding the WSON package, see the TI AN-1187 Application Report (SNOA401).
(5) In applications where high power dissipation and/or poor thermal resistance is present, the maximum ambient temperature may have to be derated. Maximum ambient temperature ($T_{A(max)}$) is dependant on the maximum operating junction temperature ($T_{J(max-op)}$), the maximum power dissipation ($P_{D(max)}$), and the junction to ambient thermal resistance in the application (θ_{JA}). This relationship is given by:
$T_{A(max)} = T_{J(max-op)} - (P_{D(max)} \times \theta_{JA})$
(6) The human body model is an 100 pF discharge through a 1.5 kΩ resistor into each pin. The machine model is a 200 pF capacitor discharged directly into each pin.

Operating Ratings (1)

Input Voltage (V_{IN})	2.5 to 6.0V
Enable Input Voltage	0 to 6.0V
Junction Temperature	−40 to +125°C
Ambient Temperature Range (2)	-40 to 85°C

(1) Absolute Maximum Ratings are limits beyond which damage to the device may occur. Operating Ratings are conditions under which operation of the device is guaranteed. Operating Ratings do not imply guaranteed performance limits. For guaranteed performance limits and associated test conditions, see the Electrical Characteristics tables.
(2) In applications where high power dissipation and/or poor thermal resistance is present, the maximum ambient temperature may have to be derated. Maximum ambient temperature ($T_{A(max)}$) is dependant on the maximum operating junction temperature ($T_{J(max-op)}$), the maximum power dissipation ($P_{D(max)}$), and the junction to ambient thermal resistance in the application (θ_{JA}). This relationship is given by:
$T_{A(max)} = T_{J(max-op)} - (P_{D(max)} \times \theta_{JA})$

Thermal Properties (1)

Junction to Ambient Thermal Resistance	
θ_{JA} (WSON pkg.)	88°C/W
θ_{JA} (DSBGA pkg.)	255°C/W

(1) Junction to ambient thermal resistance is highly dependant on the application and board layout. In applications where high thermal dissipation is possible, special care must be paid to thermal issues in the board design.

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Electrical Characteristics

Unless otherwise noted, V_{EN} = 1.5, V_{IN} = V_{OUT} + 1.0V, C_{IN} = 1 µF, I_{OUT} = 1 mA, C_{OUT} = 1 µF, c_{BP} = 0.01 µF. Typical values and limits appearing in normal type apply for T_J = 25°C. Limits appearing in **boldface** type apply over the full temperature range for operation, −40 to +125°C. (1) (2)

Symbol	Parameter	Conditions	Typical	Limit		Units
				Min	Max	
V_{IN}	Input Voltage			2.5	6.0	V
DEVICE OUTPUT: 1.5 ≤ V_{OUT} < 1.8V						
ΔV_{OUT}	Output Voltage Tolerance	I_{OUT} = 1 mA		-50	50	mV
				-75	**75**	
	Line Regulation Error	V_{IN} = ($V_{OUT(NOM)}$+1.0V) to 6.0V, I_{OUT} = 1 mA		**-3.5**	**3.5**	mV/V
	DSBGA Load Regulation Error	I_{OUT} = 1 mA to 150 mA	10		**75**	µV/mA
	WSON Load Regulation Error	I_{OUT} = 1 mA to 150 mA	70		**125**	µV/mA
PSRR	Power Supply Rejection Ratio (3)	f = 1 kHz, I_{OUT} = 1 mA	55			dB
		f = 10 kHz, I_{OUT} = 1 mA	53			
DEVICE OUTPUT: 1.8 ≤ V_{OUT} < 2.5V						
ΔV_{OUT}	Output Voltage Tolerance	I_{OUT} = 1 mA		-50	50	mV
				−75	**75**	
	DSBGA Line Regulation Error	V_{IN} = ($V_{OUT(NOM)}$+1.0V) to 6.0V, I_{OUT} = 1 mA		**−2.5**	**2.5**	mV/V
	WSON Line Regulation Error	V_{IN} = ($V_{OUT(NOM)}$+1.0V) to 6.0V, I_{OUT} = 1 mA		**−3.5**	**3.5**	mV/V
	DSBGA Load Regulation Error	I_{OUT} = 1 mA to 150 mA	10		**75**	µV/mA
	WSON Load Regulation Error	I_{OUT} = 1 mA to 150 mA	80		**125**	µV/mA
PSRR	Power Supply Rejection Ratio (3)	f = 1 kHz, I_{OUT} = 1 mA	55			dB
		f = 10 kHz, I_{OUT} = 1 mA	50			
DEVICE OUTPUT: 2.5 ≤ V_{OUT} ≤ 3.3V						
ΔV_{OUT}	Output Voltage Tolerance	I_{OUT} = 1 mA		-2	2	% of $V_{OUT(NOM)}$
				−3	**3**	
	Line Regulation Error	V_{IN} = ($V_{OUT(NOM)}$+1.0V) to 6.0V, I_{OUT} = 1 mA		**−0.1**	**0.1**	%/V
	DSBGA Load Regulation Error	I_{OUT} = 1 mA to 150 mA	0.0004		**0.002**	%/mA
	WSON Load Regulation Error	I_{OUT} = 1 mA to 150 mA	0.002		**0.005**	%/mA
	Dropout Voltage	I_{OUT} = 1 mA	0.4		**2**	mV
		I_{OUT} = 150 mA	60		**100**	
PSRR	Power Supply Rejection Ratio (3)	f = 1 kHz, I_{OUT} = 1 mA	60			dB
		f = 10 kHz, I_{OUT} = 1 mA	50			
FULL V_{OUT} RANGE						
I_{LOAD}	Load Current	See (4) and (3)		0		µA

(1) All limits are guaranteed. All electrical characteristics having room-temperature limits are tested during production at T_J = 25°C or correlated using Statistical Quality Control methods. Operation over the temperature specification is guaranteed by correlating the electrical characteristics to process and temperature variations and applying statistical process control.
(2) $V_{OUT(NOM)}$ is the stated output voltage option for the device.
(3) This electrical specification is guaranteed by design.
(4) The device maintains a stable, regulated output voltage without load.

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Electrical Characteristics (continued)

Unless otherwise noted, V_{EN} = 1.5, V_{IN} = V_{OUT} + 1.0V, C_{IN} = 1 µF, I_{OUT} = 1 mA, C_{OUT} = 1 µF, c_{BP} = 0.01 µF. Typical values and limits appearing in normal type apply for T_J = 25°C. Limits appearing in **boldface** type apply over the full temperature range for operation, −40 to +125°C. (1) (2)

Symbol	Parameter	Conditions	Typical	Limit		Units
				Min	Max	
I_Q	Quiescent Current	V_{EN} = 1.5V, I_{OUT} = 0 mA	85		**150**	µA
		V_{EN} = 1.5V, I_{OUT} = 150 mA	140		**200**	
		V_{EN} = 0.4V	0.003		**1.5**	
I_{SC}	Short Circuit Current Limit		450			mA
E_N	Output Noise Voltage (3)	BW = 10 Hz to 100 kHz, V_{IN} = 4.2V, I_{OUT} = 1mA	25			µVrms
$T_{SHUTDOWN}$	Thermal Shutdown	Temperature	160			°C
		Hysteresis	20			
ENABLE CONTROL CHARACTERISTICS						
I_{EN}	Maximum Input Current at V_{EN} Input	V_{EN} = 0.0V and V_{IN} = 6.0V	0.001			µA
V_{IL}	Low Input Threshold				**0.4**	V
V_{IH}	High Input Threshold			**0.9**		V
TIMING CHARACTERISTICS						
T_{ON}	Turn On Time (3)	To 95% Level (5)	30			µs
T_{OFF}	Turn Off Time (3)	To 5% Level (6)	175			µs

(5) Time from V_{EN} = 0.9V to V_{OUT} = 95% ($V_{OUT(NOM)}$)
(6) Time from V_{EN} = 0.4V to V_{OUT} = 5% ($V_{OUT(NOM)}$)

Recommended Output Capacitor

Symbol	Parameter	Conditions	VALUE	Limit		Units
				Min	Max	
C_{OUT}	Output Capacitor	Capacitance (1)	1.0	0.70		µF
		ESR		5	500	mΩ

(1) The capacitor tolerance should be ±30% or better over the temperature range. The recommended capacitor type is X7R however, dependant on the application X5R, Y5V, and Z5U can also be used.

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INPUT TEST SIGNALS

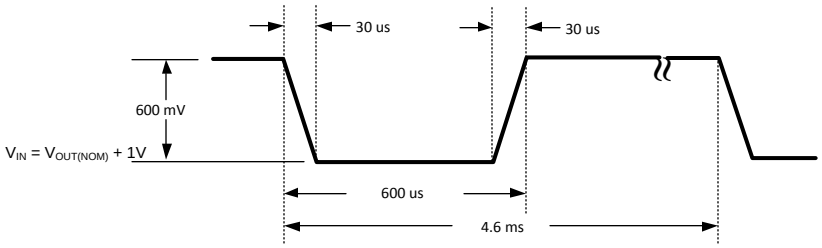

Figure 1. Line Transient Response Input Test Signal

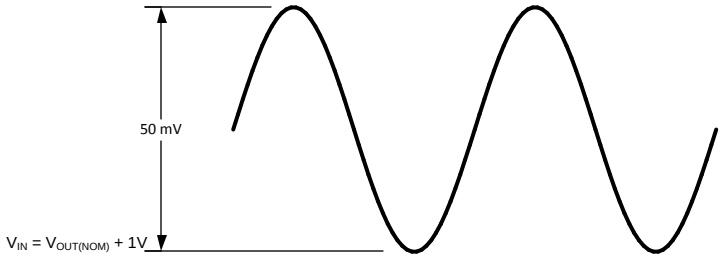

Figure 2. PSRR Input Test Signal

TYPICAL PERFORMANCE CHARACTERISTICS

Unless otherwise specified, $C_{IN} = C_{OUT} = 1.0\ \mu F$ Ceramic, $V_{IN} = V_{OUT} + 1.0V$, $T_A = 25°C$, Enable pin is tied to V_{IN}.

Output Voltage Change vs Temperature

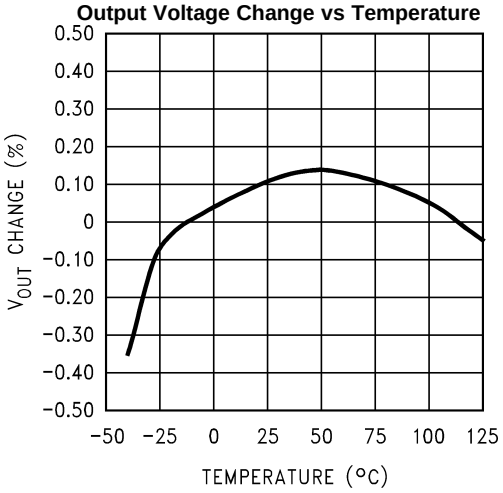

Figure 3.

Ground Current vs Load Current (1.8V V_{OUT})

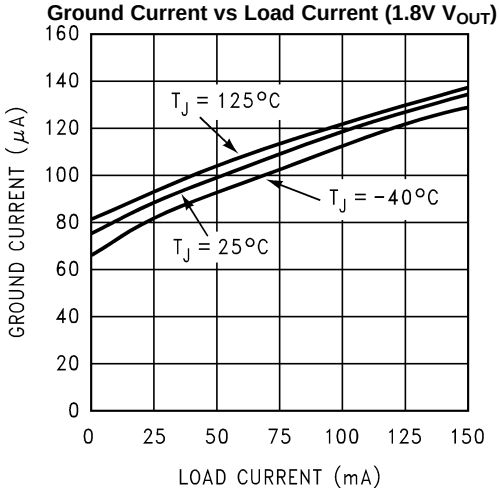

Figure 4.

Ground Current vs Load Current (2.8V V_{OUT})

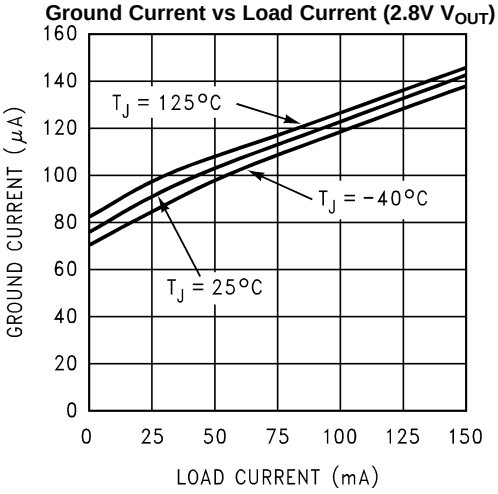

Figure 5.

Ground Current vs V_{IN} @ 25°C

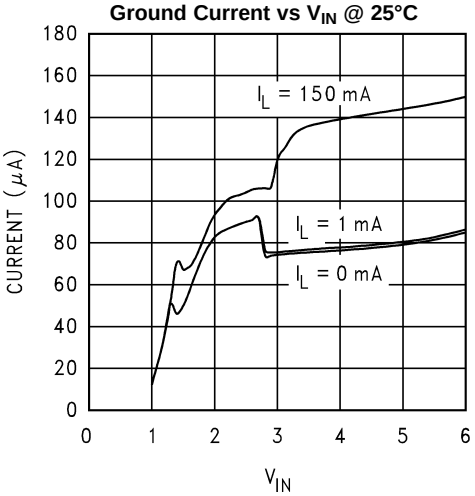

Figure 6.

Ground Current vs V_{IN} @ 125°C

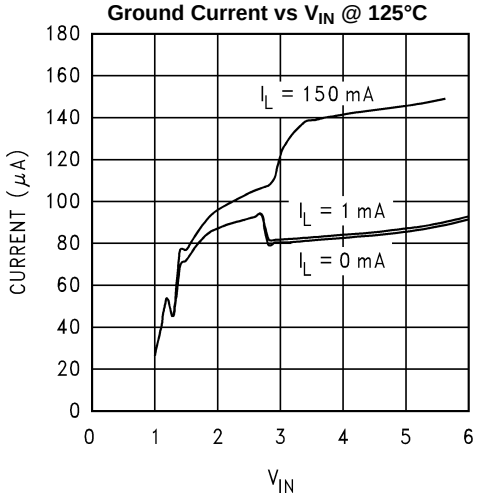

Figure 7.

Dropout vs Load Current

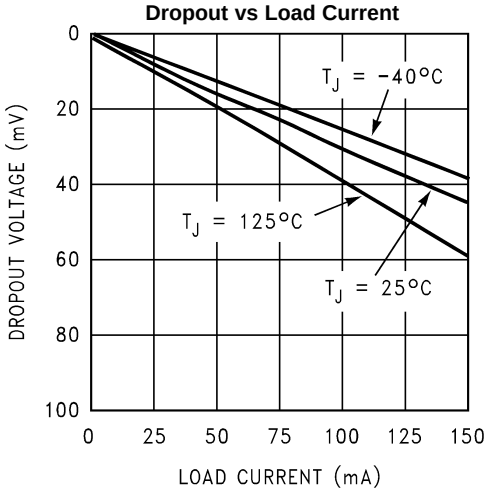

Figure 8.

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TYPICAL PERFORMANCE CHARACTERISTICS (continued)

Unless otherwise specified, $C_{IN} = C_{OUT} = 1.0$ µF Ceramic, $V_{IN} = V_{OUT} + 1.0V$, $T_A = 25°C$, Enable pin is tied to V_{IN}.

Short Circuit Current

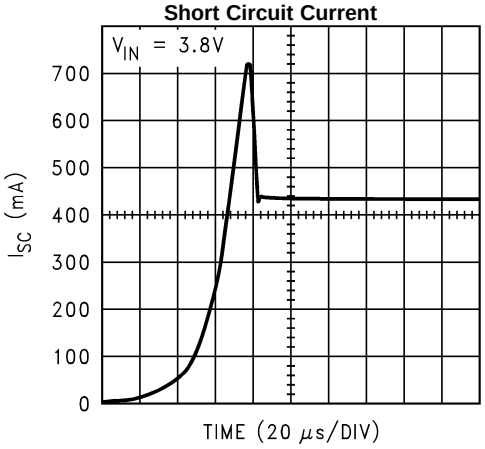

Figure 9.

Line Transient Response (V_{OUT} = 2.8V)

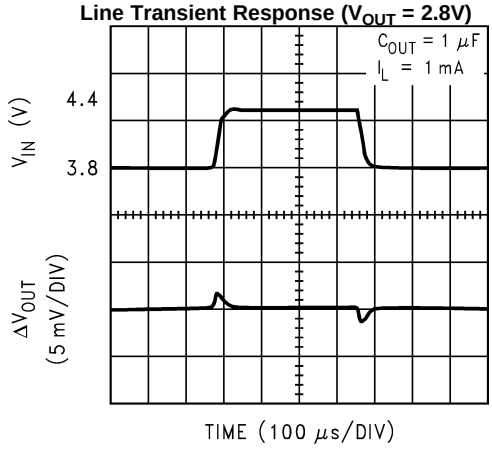

Figure 10.

Ripple Rejection (V_{OUT} = 1.8V)

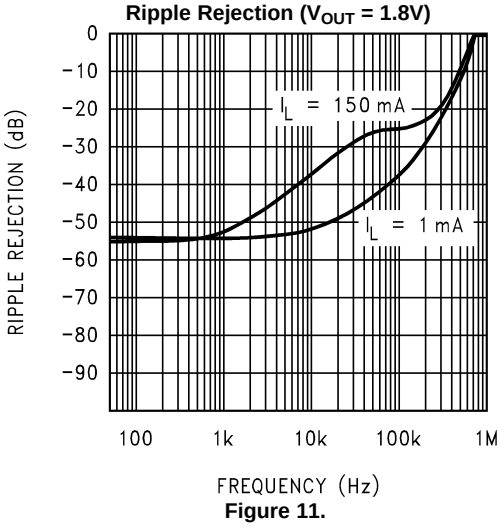

Figure 11.

Ripple Rejection (V_{OUT} = 2.8V)

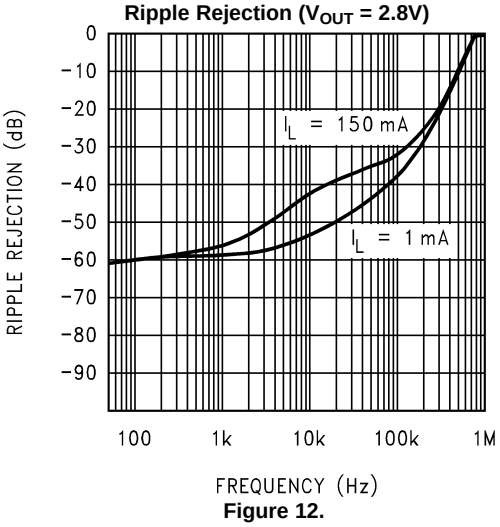

Figure 12.

Enable Start-Up Time (V_{OUT} = 2.8V)

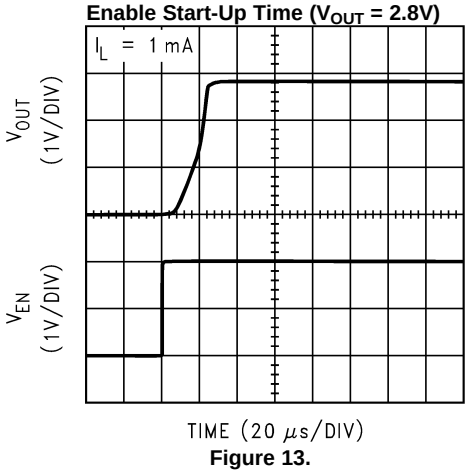

Figure 13.

Enable Start-Up Time (V_{OUT} = 2.8V)

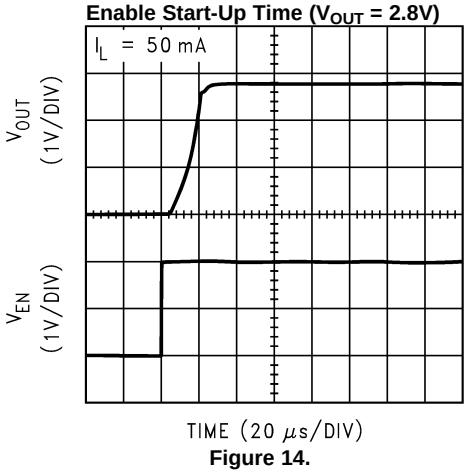

Figure 14.

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TYPICAL PERFORMANCE CHARACTERISTICS (continued)

Unless otherwise specified, $C_{IN} = C_{OUT} = 1.0\ \mu F$ Ceramic, $V_{IN} = V_{OUT} + 1.0V$, $T_A = 25°C$, Enable pin is tied to V_{IN}.

Enable Start-Up Time (V_{OUT} = 1.8V)

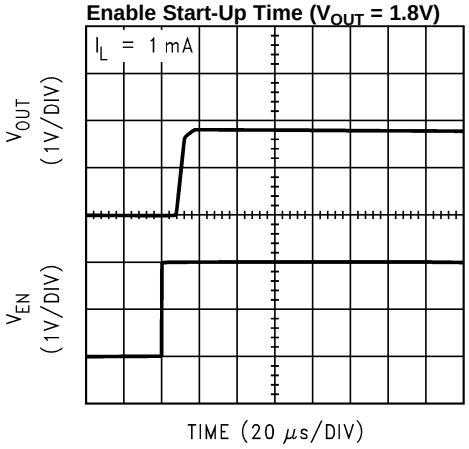

Figure 15.

Enable Start-Up Time (V_{OUT} = 1.8V)

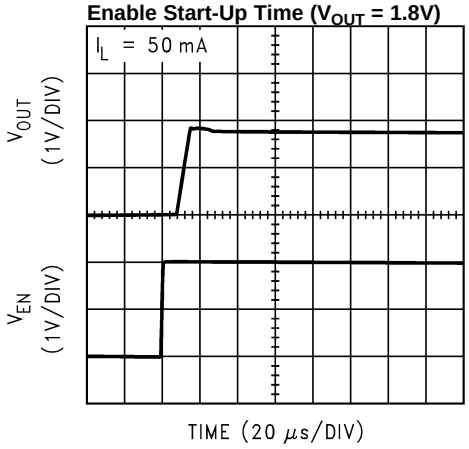

Figure 16.

Turn-Off Time (V_{OUT} = 2.8V)

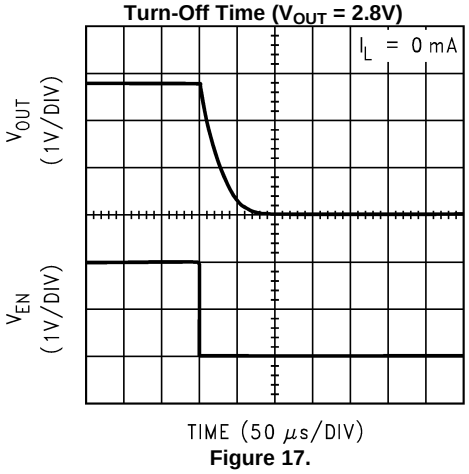

Figure 17.

Turn-Off Time (V_{OUT} = 1.8V)

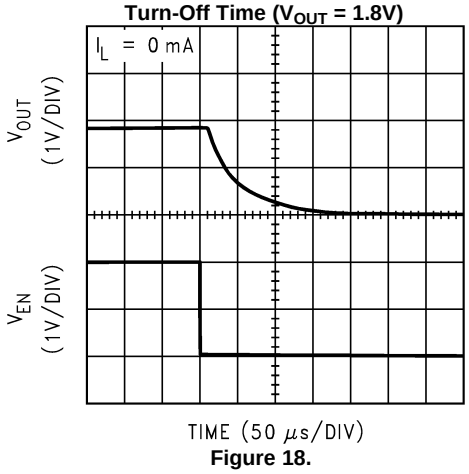

Figure 18.

Load Transient Response (V_{OUT} = 2.8V)

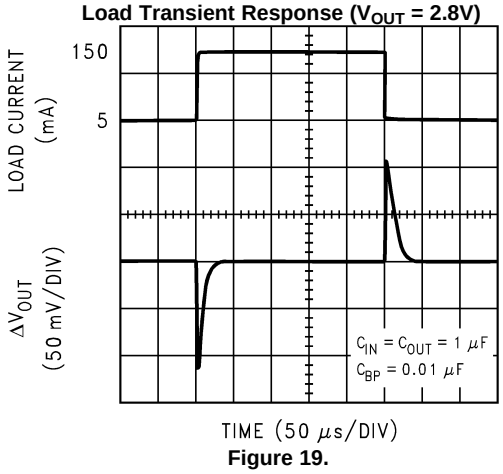

Figure 19.

Load Transient Response (V_{OUT} = 1.8V)

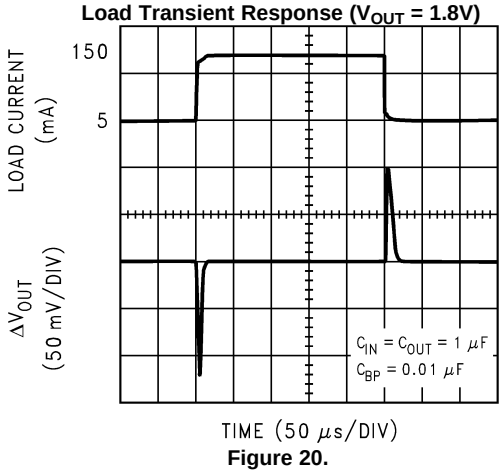

Figure 20.

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APPLICATION HINTS

POWER DISSIPATION AND DEVICE OPERATION

The permissible power dissipation for any package is a measure of the capability of the device to pass heat from the power source, the junctions of the IC, to the ultimate heat sink, the ambient environment. Thus the power dissipation is dependent on the ambient temperature and the thermal resistance across the various interfaces between the die and ambient air.

Thermal Resistance Figure

Re-stating the equation given in note 5 of the Absolute Maximum Ratings section:

$$T_{A(max)} = T_{J(max\text{-}op)} - (P_{D(max)} \times \theta_{JA})$$

the allowable power dissipation for the device in a given package can be calculated:

$$P_D = \frac{(T_{J(MAX)} - T_A)}{\theta_{JA}} \quad (1)$$

With a θ_{JA} = 255°C/W, the device in the DSBGA package returns a value of 392 mW with a maximum junction temperature of 125°C.

With a θ_{JA} = 88°C/W, the device in the WSON package returns a value of 1.136 mW with a maximum junction temperature of 125°C.

The actual power dissipation across the device can be represented by the following equation:

$$P_D = (V_{IN} - V_{OUT}) \times I_{OUT} \quad (2)$$

This establishes the relationship between the power dissipation allowed due to thermal consideration, the voltage drop across the device, and the continuous current capability of the device. These two equations should be used to determine the optimum operating conditions for the device in the application.

EXTERNAL CAPACITORS

In common with most regulators, the LP3995 requires external capacitors to ensure stable operation. The LP3995 is specifically designed for portable applications requiring minimum board space and smallest components. These capacitors must be correctly selected for good performance.

INPUT CAPACITOR

An input capacitor is required for stability. It is recommended that a 1.0 µF capacitor be connected between the LP3995 input pin and ground (this capacitance value may be increased without limit).

This capacitor must be located a distance of not more than 1 cm from the input pin and returned to a clean analogue ground. Any good quality ceramic, tantalum, or film capacitor may be used at the input.

Important: Tantalum capacitors can suffer catastrophic failures due to surge current when connected to a low-impedance source of power (like a battery or a very large capacitor). If a tantalum capacitor is used at the input, it must be guaranteed by the manufacturer to have a surge current rating sufficient for the application.

There are no requirements for the **ESR** (Equivalent Series Resistance) on the input capacitor, but tolerance and temperature coefficient must be considered when selecting the capacitor to ensure the capacitance will remain ≅ 1.0 µF over the entire operating temperature range.

OUTPUT CAPACITOR

The LP3995 is designed specifically to work with very small ceramic output capacitors. A ceramic capacitor (dielectric types Z5U, Y5V or X7R) in the 1.0 [to 10 µF] range, and with ESR between 5 mΩ to 500 mΩ, is suitable in the LP3995 application circuit.

For this device the output capacitor should be connected between the V_{OUT} pin and ground.

It may also be possible to use tantalum or film capacitors at the device output, V_{OUT}, but these are not as attractive for reasons of size and cost (see CAPACITOR CHARACTERISTICS).

The output capacitor must meet the requirement for the minimum value of capacitance and also have an ESR value that is within the range 5 mΩ to 500 mΩ for stability.

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NO-LOAD STABILITY

The LP3995 will remain stable and in regulation with no external load. This is an important consideration in some circuits, for example CMOS RAM keep-alive applications.

CAPACITOR CHARACTERISTICS

The LP3995 is designed to work with ceramic capacitors on the output to take advantage of the benefits they offer. For capacitance values in the range of 1 µF to 4.7 µF, ceramic capacitors are the smallest, least expensive and have the lowest ESR values, thus making them best for eliminating high frequency noise. The ESR of a typical 1 µF ceramic capacitor is in the range of 20 mΩ to 40 mΩ, which easily meets the ESR requirement for stability for the LP3995.

The temperature performance of ceramic capacitors varies by type. Most large value ceramic capacitors (≥ 2.2 µF) are manufactured with Z5U or Y5V temperature characteristics, which results in the capacitance dropping by more than 50% as the temperature goes from 25°C to 85°C.

A better choice for temperature coefficient in a ceramic capacitor is X7R. This type of capacitor is the most stable and holds the capacitance within ±15% over the temperature range. Tantalum capacitors are less desirable than ceramic for use as output capacitors because they are more expensive when comparing equivalent capacitance and voltage ratings in the 1 µF to 4.7 µF range.

Another important consideration is that tantalum capacitors have higher ESR values than equivalent size ceramics. This means that while it may be possible to find a tantalum capacitor with an ESR value within the stable range, it would have to be larger in capacitance (which means bigger and more costly) than a ceramic capacitor with the same ESR value. It should also be noted that the ESR of a typical tantalum will increase about 2:1 as the temperature goes from 25°C down to −40°C, so some guard band must be allowed.

NOISE BYPASS CAPACITOR

A bypass capacitor should be connected between the C_{BP} pin and ground to significantly reduce the noise at the regulator output. This device pin connects directly to a high impedance node within the bandgap reference circuitry. Any significant loading on this node will cause a change on the regulated output voltage. For this reason, DC leakage current through this pin must be kept as low as possible for best output voltage accuracy.

The use of a 0.01 µF bypass capacitor is strongly recommended to prevent overshoot on the output during start-up.

The types of capacitors best suited for the noise bypass capacitor are ceramic and film. High quality ceramic capacitors with NPO or COG dielectric typically have very low leakage. Polypropolene and polycarbonate film capacitors are available in small surface-mount packages and typically have extremely low leakage current.

Unlike many other LDOs, the addition of a noise reduction capacitor does not effect the transient response of the device.

ENABLE OPERATION

The LP3995 may be switched ON or OFF by a logic input at the ENABLE pin, V_{EN}. A high voltage at this pin will turn the device on. When the enable pin is low, the regulator output is off and the device typically consumes 3 nA. If the application does not require the shutdown feature, the V_{EN} pin should be tied to V_{IN} to keep the regulator output permanently on. To ensure proper operation, the signal source used to drive the V_{EN} input must be able to swing above and below the specified turn-on/off voltage thresholds listed in the Electrical Characteristics section under V_{IL} and V_{IH}.

FAST TURN OFF AND ON

The controlled switch-off feature of the device provides a fast turn off by discharging the output capacitor via an internal FET device. This discharge is current limited by the RDSon of this switch. Fast turn-on is guaranteed by control circuitry within the reference block allowing a very fast ramp of the output voltage to reach the target voltage.

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DSBGA MOUNTING

The DSBGA package requires specific mounting techniques that are detailed in TI's AN-1112 Application Report (SNVA009). Referring to the section *Surface Mount Assembly Considerations*, it should be noted that the pad style which must be used with the 5 pin package is NSMD (non-solder mask defined) type.

For best results during assembly, alignment ordinals on the PC board may be used to facilitate placement of the DSBGA device.

DSBGA LIGHT SENSITIVITY

Exposing the DSBGA device to direct sunlight will cause incorrect operation of the device. Light sources such as halogen lamps can affect electrical performance if they are situated in proximity to the device.

Light with wavelengths in the red and infra-red part of the spectrum have the most detrimental effect thus the fluorescent lighting used inside most buildings has very little effect on performance. Tests carried out on a DSBGA test board showed a negligible effect on the regulated output voltage when brought within 1 cm of a fluorescent lamp. A deviation of less than 0.1% from nominal output voltage was observed.

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REVISION HISTORY

Changes from Revision D (March 2013) to Revision E	Page
• Changed layout of National Data Sheet to TI format	13

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LP3995ILD-1.5/NOPB	ACTIVE	WSON	NGD	6	1000	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR	-40 to 125	L020B	Samples
LP3995ILD-1.8/NOPB	ACTIVE	WSON	NGD	6	1000	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR	-40 to 125	L022B	Samples
LP3995ILD-2.8/NOPB	ACTIVE	WSON	NGD	6	1000	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR	-40 to 125	L026B	Samples
LP3995ILD-3.0/NOPB	ACTIVE	WSON	NGD	6	1000	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR	-40 to 125	L030B	Samples
LP3995ILDX-2.8/NOPB	ACTIVE	WSON	NGD	6	4500	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR	-40 to 125	L026B	Samples
LP3995ITL-1.5/NOPB	ACTIVE	DSBGA	YZR	5	250	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 125	9	Samples
LP3995ITL-1.6/NOPB	ACTIVE	DSBGA	YZR	5	250	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 125	9	Samples
LP3995ITL-1.8/NOPB	ACTIVE	DSBGA	YZR	5	250	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 125	9	Samples
LP3995ITL-1.9/NOPB	ACTIVE	DSBGA	YZR	5	250	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 125	9	Samples
LP3995ITL-2.1/NOPB	ACTIVE	DSBGA	YZR	5	250	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 125	9	Samples
LP3995ITL-2.5/NOPB	ACTIVE	DSBGA	YZR	5	250	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 125	9	Samples
LP3995ITL-2.7/NOPB	ACTIVE	DSBGA	YZR	5	250	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM		9	Samples
LP3995ITL-2.8/NOPB	ACTIVE	DSBGA	YZR	5	250	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 125	9	Samples
LP3995ITL-2.85/NOPB	ACTIVE	DSBGA	YZR	5	250	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 125	9	Samples
LP3995ITL-3.0/NOPB	ACTIVE	DSBGA	YZR	5	250	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 125	9	Samples
LP3995ITLX-1.5/NOPB	ACTIVE	DSBGA	YZR	5	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 125	9	Samples
LP3995ITLX-1.6/NOPB	ACTIVE	DSBGA	YZR	5	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 125	9	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LP3995ITLX-1.8/NOPB	ACTIVE	DSBGA	YZR	5	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 125	9	Samples
LP3995ITLX-1.9/NOPB	ACTIVE	DSBGA	YZR	5	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 125	9	Samples
LP3995ITLX-2.1/NOPB	ACTIVE	DSBGA	YZR	5	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 125	9	Samples
LP3995ITLX-2.5/NOPB	ACTIVE	DSBGA	YZR	5	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 125	9	Samples
LP3995ITLX-2.7/NOPB	ACTIVE	DSBGA	YZR	5	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM		9	Samples
LP3995ITLX-2.8/NOPB	ACTIVE	DSBGA	YZR	5	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 125	9	Samples
LP3995ITLX-2.85/NOPB	ACTIVE	DSBGA	YZR	5	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 125	9	Samples
LP3995ITLX-3.0/NOPB	ACTIVE	DSBGA	YZR	5	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 125	9	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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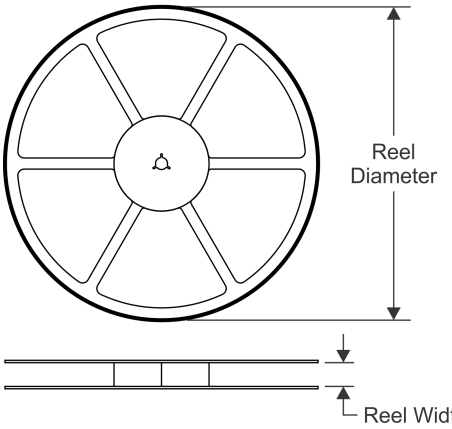
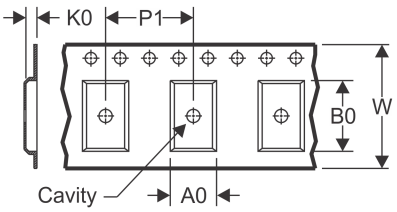
TAPE AND REEL INFORMATION

REEL DIMENSIONS

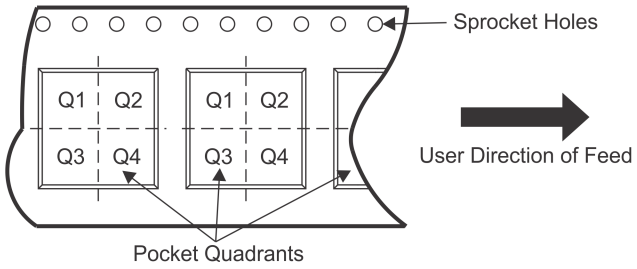


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

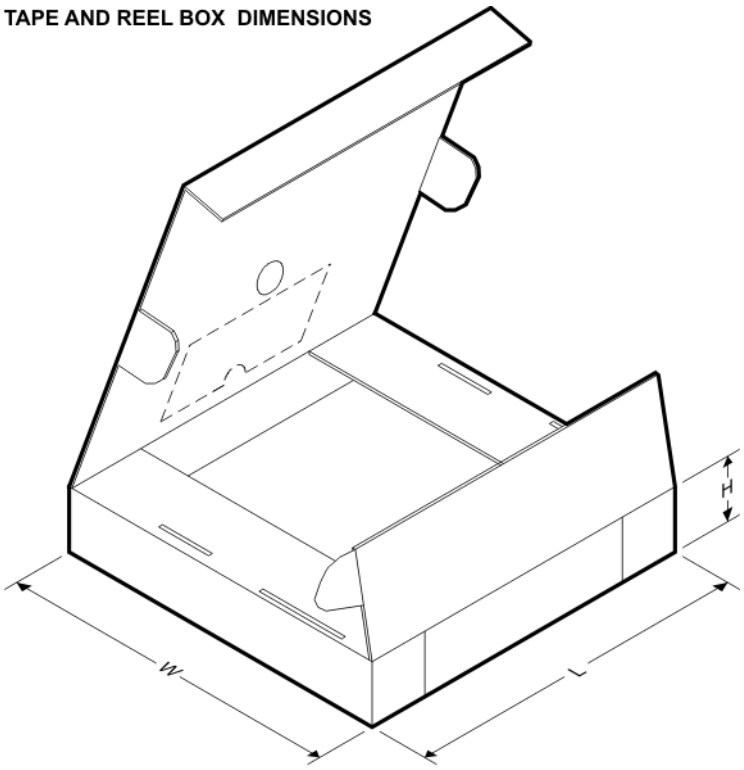


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LP3995ILD-1.5/NOPB	WSON	NGD	6	1000	178.0	12.4	3.6	3.2	1.0	8.0	12.0	Q1
LP3995ILD-1.8/NOPB	WSON	NGD	6	1000	178.0	12.4	3.6	3.2	1.0	8.0	12.0	Q1
LP3995ILD-2.8/NOPB	WSON	NGD	6	1000	178.0	12.4	3.6	3.2	1.0	8.0	12.0	Q1
LP3995ILD-3.0/NOPB	WSON	NGD	6	1000	178.0	12.4	3.6	3.2	1.0	8.0	12.0	Q1
LP3995ILDX-2.8/NOPB	WSON	NGD	6	4500	330.0	12.4	3.6	3.2	1.0	8.0	12.0	Q1
LP3995ITL-1.5/NOPB	DSBGA	YZR	5	250	178.0	8.4	1.09	1.55	0.76	4.0	8.0	Q1
LP3995ITL-1.6/NOPB	DSBGA	YZR	5	250	178.0	8.4	1.09	1.55	0.76	4.0	8.0	Q1
LP3995ITL-1.8/NOPB	DSBGA	YZR	5	250	178.0	8.4	1.09	1.55	0.76	4.0	8.0	Q1
LP3995ITL-1.9/NOPB	DSBGA	YZR	5	250	178.0	8.4	1.09	1.55	0.76	4.0	8.0	Q1
LP3995ITL-2.1/NOPB	DSBGA	YZR	5	250	178.0	8.4	1.09	1.55	0.76	4.0	8.0	Q1
LP3995ITL-2.5/NOPB	DSBGA	YZR	5	250	178.0	8.4	1.09	1.55	0.76	4.0	8.0	Q1
LP3995ITL-2.7/NOPB	DSBGA	YZR	5	250	178.0	8.4	1.09	1.55	0.76	4.0	8.0	Q1
LP3995ITL-2.8/NOPB	DSBGA	YZR	5	250	178.0	8.4	1.09	1.55	0.76	4.0	8.0	Q1
LP3995ITL-2.85/NOPB	DSBGA	YZR	5	250	178.0	8.4	1.09	1.55	0.76	4.0	8.0	Q1
LP3995ITL-3.0/NOPB	DSBGA	YZR	5	250	178.0	8.4	1.09	1.55	0.76	4.0	8.0	Q1
LP3995ITLX-1.5/NOPB	DSBGA	YZR	5	3000	178.0	8.4	1.09	1.55	0.76	4.0	8.0	Q1
LP3995ITLX-1.6/NOPB	DSBGA	YZR	5	3000	178.0	8.4	1.09	1.55	0.76	4.0	8.0	Q1
LP3995ITLX-1.8/NOPB	DSBGA	YZR	5	3000	178.0	8.4	1.09	1.55	0.76	4.0	8.0	Q1

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LP3995ITLX-1.9/NOPB	DSBGA	YZR	5	3000	178.0	8.4	1.09	1.55	0.76	4.0	8.0	Q1
LP3995ITLX-2.1/NOPB	DSBGA	YZR	5	3000	178.0	8.4	1.09	1.55	0.76	4.0	8.0	Q1
LP3995ITLX-2.5/NOPB	DSBGA	YZR	5	3000	178.0	8.4	1.09	1.55	0.76	4.0	8.0	Q1
LP3995ITLX-2.7/NOPB	DSBGA	YZR	5	3000	178.0	8.4	1.09	1.55	0.76	4.0	8.0	Q1
LP3995ITLX-2.8/NOPB	DSBGA	YZR	5	3000	178.0	8.4	1.09	1.55	0.76	4.0	8.0	Q1
LP3995ITLX-2.85/NOPB	DSBGA	YZR	5	3000	178.0	8.4	1.09	1.55	0.76	4.0	8.0	Q1
LP3995ITLX-3.0/NOPB	DSBGA	YZR	5	3000	178.0	8.4	1.09	1.55	0.76	4.0	8.0	Q1

TAPE AND REEL BOX DIMENSIONS

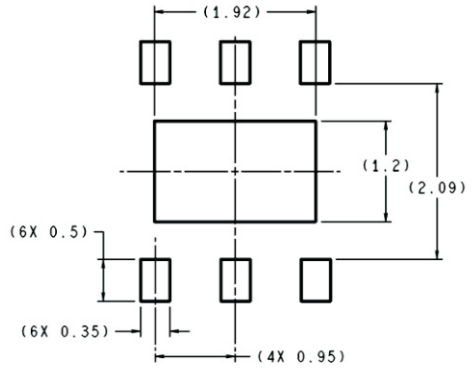


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LP3995ILD-1.5/NOPB	WSON	NGD	6	1000	213.0	191.0	55.0
LP3995ILD-1.8/NOPB	WSON	NGD	6	1000	213.0	191.0	55.0
LP3995ILD-2.8/NOPB	WSON	NGD	6	1000	213.0	191.0	55.0
LP3995ILD-3.0/NOPB	WSON	NGD	6	1000	213.0	191.0	55.0
LP3995ILDX-2.8/NOPB	WSON	NGD	6	4500	367.0	367.0	35.0
LP3995ITL-1.5/NOPB	DSBGA	YZR	5	250	210.0	185.0	35.0
LP3995ITL-1.6/NOPB	DSBGA	YZR	5	250	210.0	185.0	35.0
LP3995ITL-1.8/NOPB	DSBGA	YZR	5	250	210.0	185.0	35.0
LP3995ITL-1.9/NOPB	DSBGA	YZR	5	250	210.0	185.0	35.0
LP3995ITL-2.1/NOPB	DSBGA	YZR	5	250	210.0	185.0	35.0

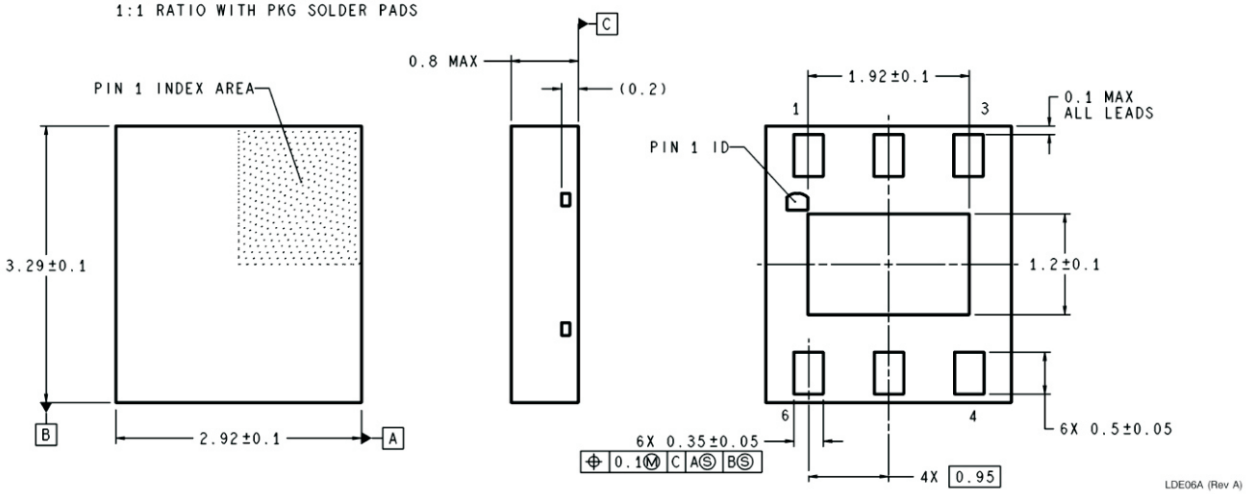
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LP3995ITL-2.5/NOPB	DSBGA	YZR	5	250	210.0	185.0	35.0
LP3995ITL-2.7/NOPB	DSBGA	YZR	5	250	210.0	185.0	35.0
LP3995ITL-2.8/NOPB	DSBGA	YZR	5	250	210.0	185.0	35.0
LP3995ITL-2.85/NOPB	DSBGA	YZR	5	250	210.0	185.0	35.0
LP3995ITL-3.0/NOPB	DSBGA	YZR	5	250	210.0	185.0	35.0
LP3995ITLX-1.5/NOPB	DSBGA	YZR	5	3000	210.0	185.0	35.0
LP3995ITLX-1.6/NOPB	DSBGA	YZR	5	3000	210.0	185.0	35.0
LP3995ITLX-1.8/NOPB	DSBGA	YZR	5	3000	210.0	185.0	35.0
LP3995ITLX-1.9/NOPB	DSBGA	YZR	5	3000	210.0	185.0	35.0
LP3995ITLX-2.1/NOPB	DSBGA	YZR	5	3000	210.0	185.0	35.0
LP3995ITLX-2.5/NOPB	DSBGA	YZR	5	3000	210.0	185.0	35.0
LP3995ITLX-2.7/NOPB	DSBGA	YZR	5	3000	210.0	185.0	35.0
LP3995ITLX-2.8/NOPB	DSBGA	YZR	5	3000	210.0	185.0	35.0
LP3995ITLX-2.85/NOPB	DSBGA	YZR	5	3000	210.0	185.0	35.0
LP3995ITLX-3.0/NOPB	DSBGA	YZR	5	3000	210.0	185.0	35.0

NGD0006A

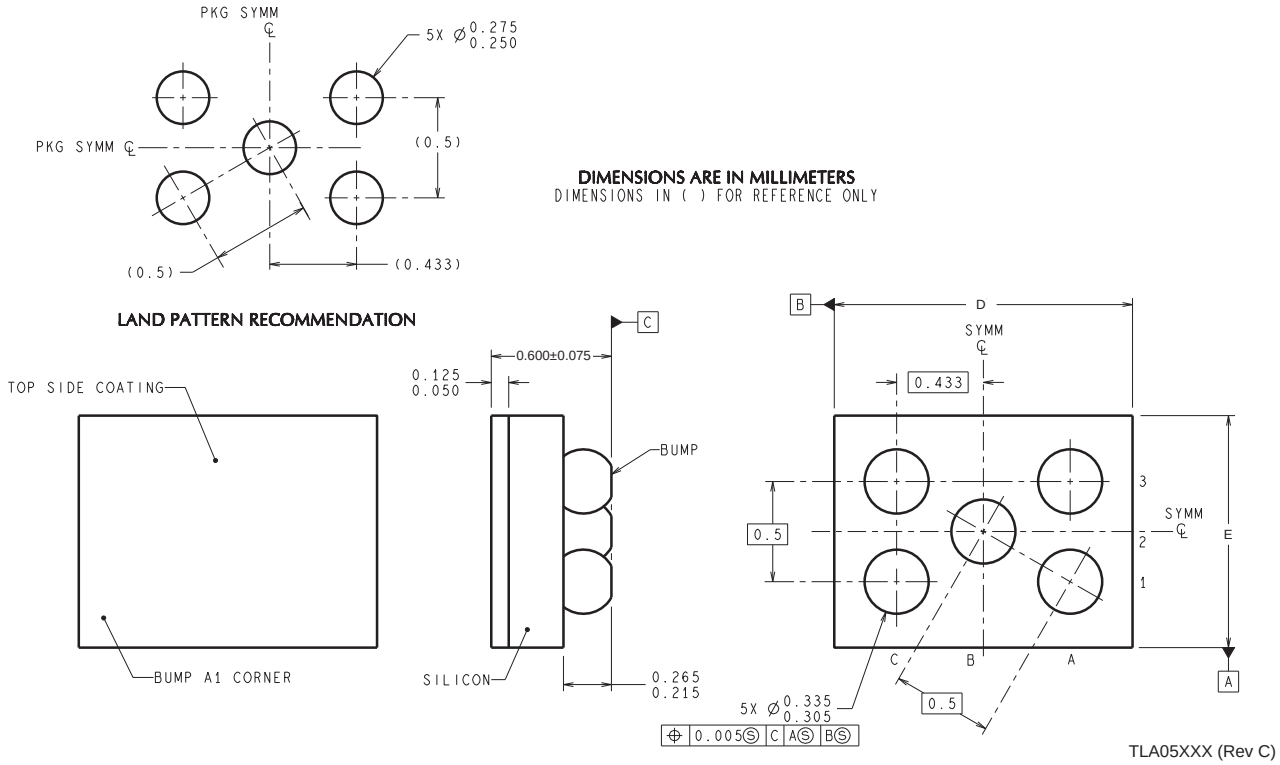


RECOMMENDED LAND PATTERN
1:1 RATIO WITH PKG SOLDER PADS

DIMENSIONS ARE IN MILLIMETERS



YZR0005



D: Max = 1.502 mm, Min =1.441 mm

E: Max = 1.045 mm, Min =0.984 mm

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NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
B. This drawing is subject to change without notice.

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